NEW GOLD BONDING WIRE

Abstract

The present invention relates to bonding wires consisting of gold, (a) platinum, (b) yttrium, (c) at least one component selected from the group consisting of calcium, cerium, germanium and palladium and (d) further components. The the sum of the amounts of components (a), (b), (c) and (d) is from 32 to 100 wt.-ppm, the sum of the amounts of Pt and Y is in the range of 30 to 90 wt.-ppm and the sum of the amounts of Ca and Ce is below 20 wt.-ppm. The invention further relates to a process for manufacturing, the use and a ball-bond arrangement comprising such a wire.

(Fig. 1 B)